Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.032 x .032”**

**.037”**

**.037”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .032” X .032”**

**Backside Potential: Cathode**

**Mask Ref: CZENR-O38**

**APPROVED BY: DK DIE SIZE .037” X .037” DATE: 11/10/21**

**MFG: MICROSEMI / CDI THICKNESS .010” P/N: 1N6082**

**DG 10.1.2**

#### Rev B, 7/19/02